

**IN THE TITLE**

Please replace the current title, "Multi-Directional Wiring On A Single Metal Layer" with "Integrated Circuit Wiring Architectures To Support Independent Designs."

**IN THE SPECIFICATION**

On page 1, line 1, please insert--

**Cross Reference to Related Applications**

This application is a continuation application of United States Patent Application entitled " Multi-Directional Wiring On A Single Metal Layer " filed on December 6, 2000, and having the Serial No. \_\_\_\_\_.

On page 2, line 13 – page 4, line 8, please delete the “Summary of the Invention”, and insert therein a new Summary of the Invention as follows:

**SUMMARY OF THE INVENTION**

An integrated circuit employs diagonal wiring geometries to provide noise immunity from Manhattan wiring geometries. Diagonal wires are routed over pre-configured or pre-designed blocks. The pre-configured blocks consist of self-contained sections within one or more metal layers of the integrated circuit, and implement Manhattan wiring geometries. The pre-configured blocks are not affected by the diagonal wires deposited on metal layers above them. The pre-configured blocks may include a memory, small cells that implement simple logic